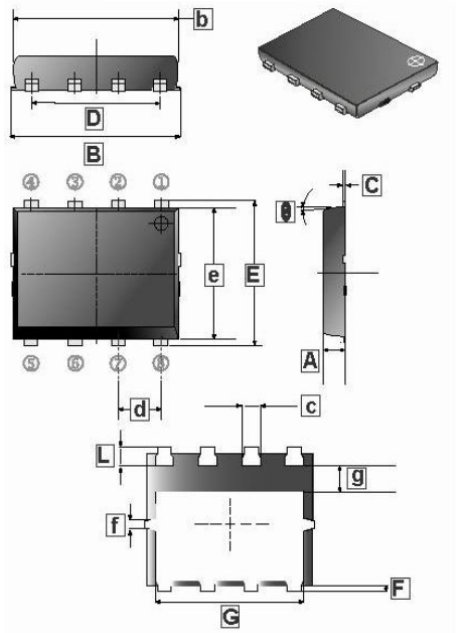
Elektronische Bauelemente

SSP7492N

6.2A, 150V, $R_{DS(ON)}$ 88 mΩ
N-Channel Enhancement MOSFET

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

SOP-8PP



DESCRIPTION

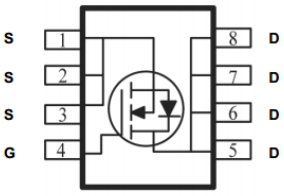
These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $R_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

FEATURES

- Low $R_{DS(on)}$ provides higher efficiency and extends battery life.
- Low thermal impedance copper leadframe SOP-8PP saves board space.
- Fast switching speed.
- High performance trench technology.

PACKAGE INFORMATION

Package	MPQ	Leader Size
SOP-8PP	3K	13 inch



REF.	Millimeter Min.	Millimeter Max.	REF.	Millimeter Min.	Millimeter Max.
A	0.85	1.00	θ	0°	10°
B	5.3 BSC.		b	5.2 BCS	
C	0.15	0.25	c	0.30	0.50
D	3.8 BCS.		d	1.27BSC	
E	6.05 BCS.		e	5.55 BCS.	
F	0.03	0.30	f	0.10	0.40
G	4.35 BCS.		g	1.2 BCS.	
L	0.40	0.70			

ABSOLUTE MAXIMUM RATINGS (T_A=25°C unless otherwise specified)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	150	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current [1]	T_A=25°C	I_D	6.2	A
	T_A=70°C		5	
Pulsed Drain Current [2]		I_{DM}	30	A
Continuous Source Current (Diode Conduction) [1]		I_S	6.7	A
Power Dissipation [1]	T_A=25°C	P_D	5	W
	T_A=70°C		3.2	
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55~150	°C
Thermal Resistance Data				
Maximum Junction to Ambient [1]	t≦10 sec	$R_{\theta JA}$	25	°C / W
	Steady State		65	

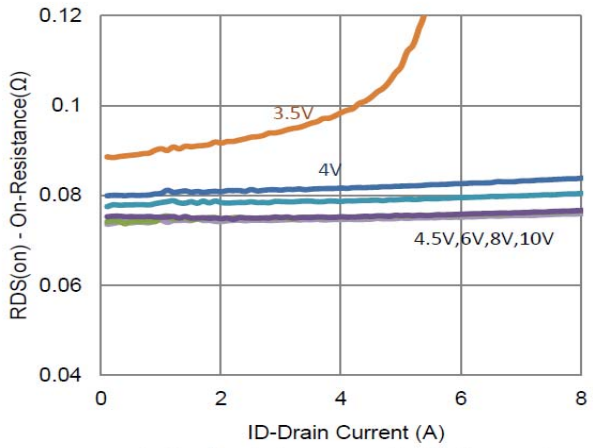
Notes:
1. Surface Mounted on 1" x 1" FR4 Board.
2. Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise specified)

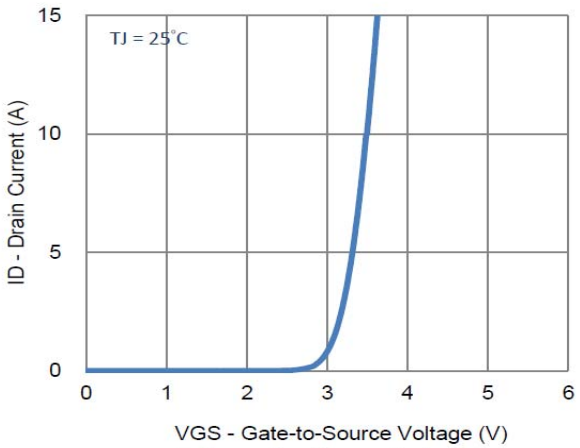
Parameter	Symbol	Min	Typ	Max	Unit	Test condition
Static						
Gate-Threshold Voltage	$V_{GS(th)}$	1	-	-	V	V_{DS}=V_{GS}, I_D=250μA
Gate-Body Leakage	I_{GSS}	-	-	±100	nA	V_{DS}=0, V_{GS}= ±20V
Zero Gate Voltage Drain Current	I_{DSS}	-	-	1	μA	V_{DS}=120V, V_{GS}=0
		-	-	25		V_{DS}=120V, V_{GS}=0,T_J=55°C
On-State Drain Current [1]	$I_{D(ON)}$	15	-	-	A	V_{DS}=5V, V_{GS}=10V
Drain-Source On-Resistance [1]	$R_{DS(ON)}$	-	-	88	mΩ	V_{GS}=10V, I_D=5A
		-	-	96		V_{GS}=5.5V, I_D=4A
Forward Transconductance [1]	g_{FS}	-	32	-	S	V_{DS}=15V,,I_D=5A
Diode Forward Voltage [1]	V_{SD}	-	0.75	-	V	I_S=3.4A, V_{GS}=0
Dynamic [2]						
Total Gate Charge	Q_g	-	23	-	nC	I_D=5A V_{DS}=75V V_{GS}=5.5V
Gate-Source Charge	Q_{gs}	-	7.4	-		
Gate-Drain Charge	Q_{gd}	-	9	-		
Turn-On Delay Time	$Td_{(ON)}$	-	14	-	nS	I_D=5A, V_{DS}=75V V_{GEN}=10V R_L=15Ω, R_{GEN}=6Ω
Rise Time	T_r	-	15	-		
Turn-Off Delay Time	$Td_{(OFF)}$	-	70	-		
Fall Time	T_f	-	31	-		
Input Capacitance	C_{iss}	-	2599	-	pF	V_{DS}=15V, V_{GS}=0, f=1MHz
Output Capacitance	C_{oss}	-	167	-		
Reverse Transfer Capacitance	C_{rss}	-	90	-		

Notes:
1. Pulse test：PW≦300μs duty cycle≦2%.
2. Guaranteed by design, not subject to production testing.

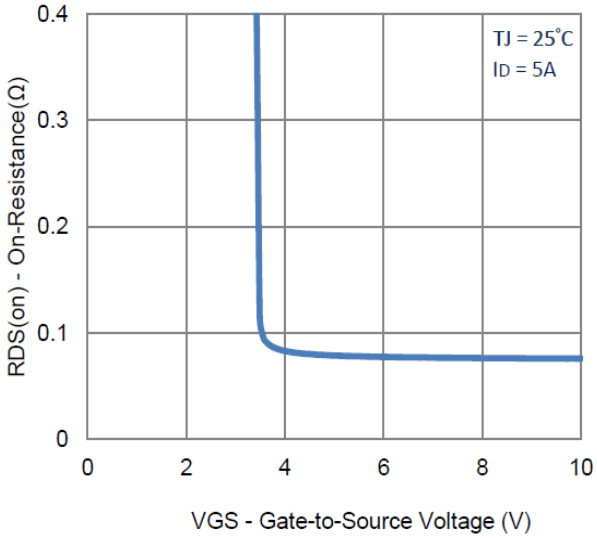
ELECTRICAL CHARACTERISTICS CURVE



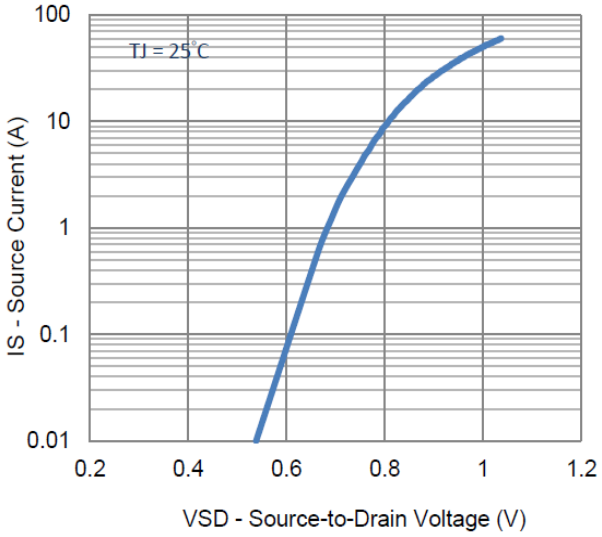
1. On-Resistance vs. Drain Current



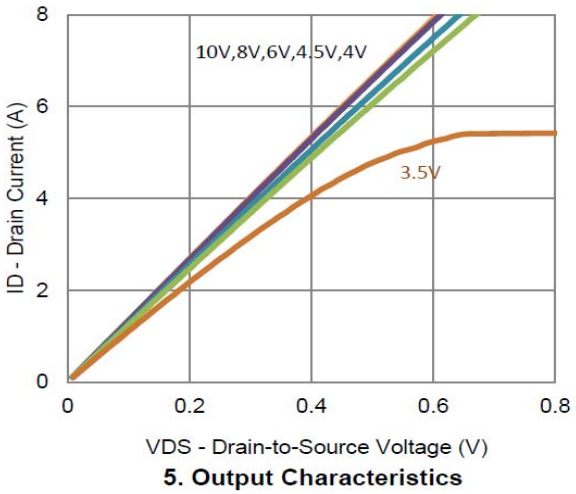
2. Transfer Characteristics



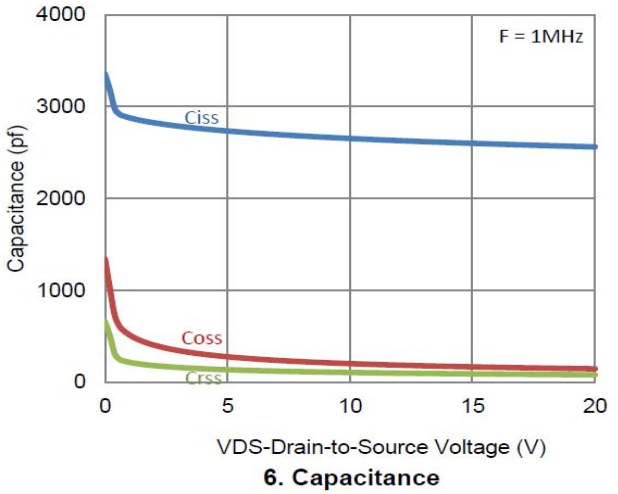
3. On-Resistance vs. Gate-to-Source Voltage



4. Drain-to-Source Forward Voltage

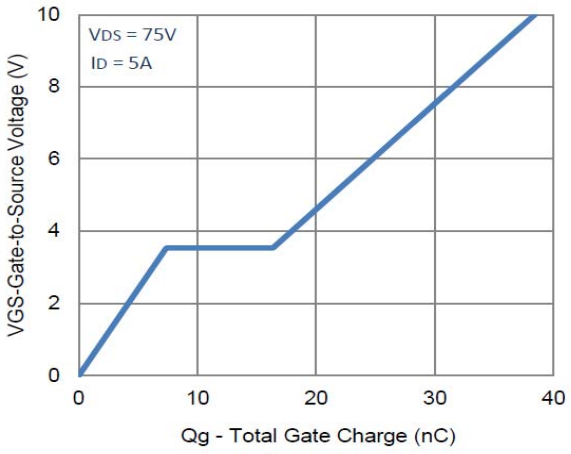


5. Output Characteristics

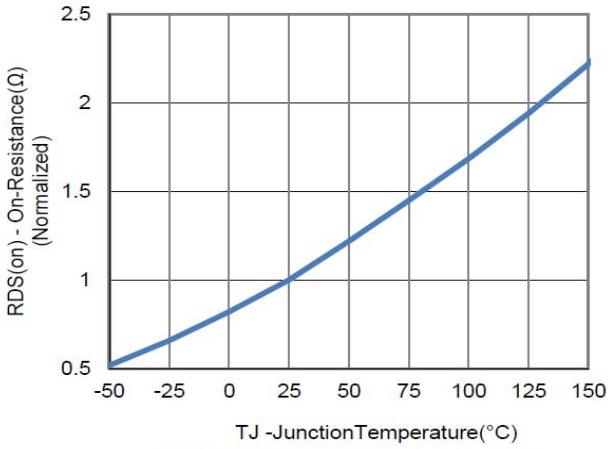


6. Capacitance

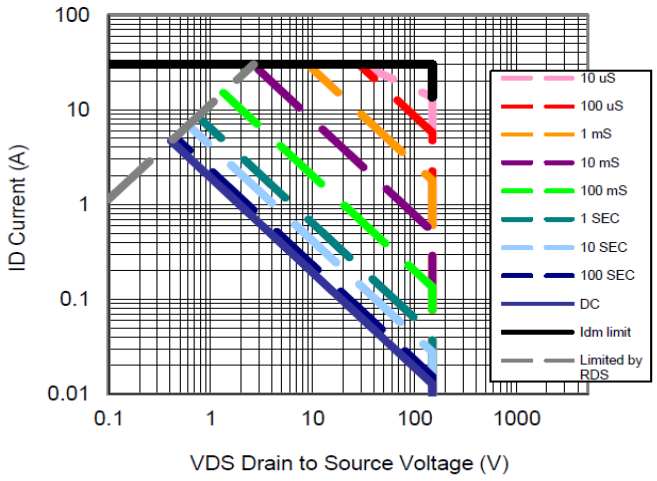
ELECTRICAL CHARACTERISTICS CURVE



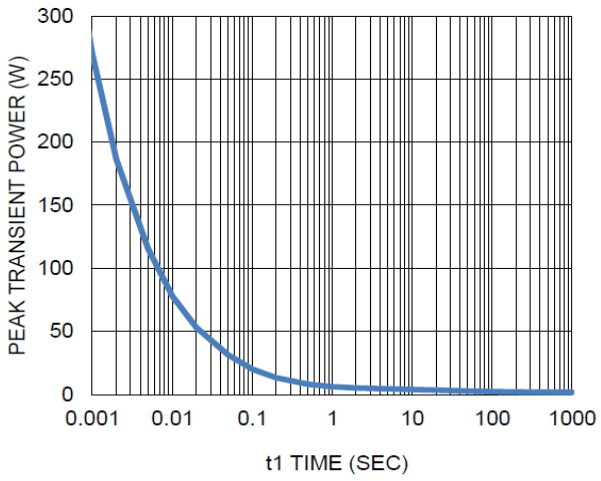
7. Gate Charge



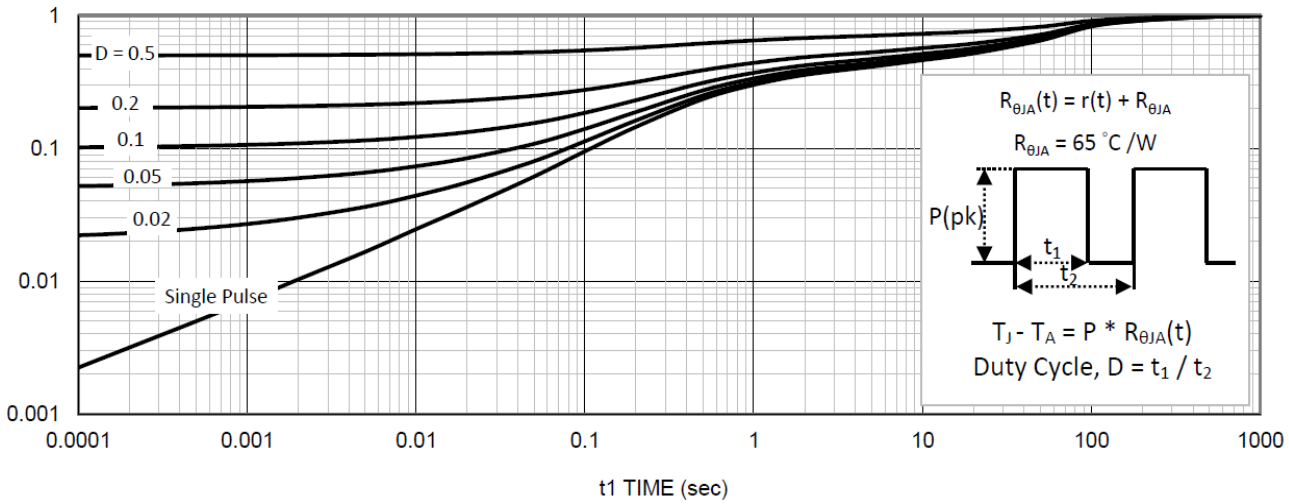
8. Normalized On-Resistance Vs Junction Temperature



9. Safe Operating Area



10. Single Pulse Maximum Power Dissipation



11. Normalized Thermal Transient Junction to Ambient